RESIN COMPOSITION

ABSTRACT

A resin composition includes:

(A) an epoxy resin that is solid at 25°C;

(B) an inorganic filler; and

(C) at least one resin selected from the group consisting of a functional group-containing saturated butadiene resin that is liquid at 25°C, a functional group-containing unsaturated butadiene resin that is liquid at 25°C, and a functional group-containing acrylic resin having a glass transition temperature of 25°C or lower, wherein

when the content of a non-volatile component in the resin composition is assumed to be 100% by mass, the content of the (B) component is 40% by mass or more, and

when the content of a resin component is assumed to be 100% by mass, the content of the (C) component is 10 to 40% by mass.

[No Suitable Figure]